

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-8 (Canceled)

9. (Currently Amended): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element at a front surface of a substrate;  
polishing a back surface of the substrate by a chemical mechanical polishing method; and

bonding a color filter at [a] the polished back surface of the substrate.

10. (Currently Amended): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being electrically connected to the semiconductor element at a front surface of a substrate;  
polishing a back surface of the substrate by a chemical mechanical polishing method; and

bonding a color filter at [a] the polished back surface of the substrate.

11. (Currently Amended): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element at a front surface of a first substrate; and  
bonding a transparent substrate comprising at least a colored layer at a back surface of the first substrate,

said method further comprising a step of bonding an antireflection film or a polarization plate to the transparent substrate.

12. (Currently Amended): A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being electrically connected to the semiconductor element at a front surface of a first substrate; and

bonding a transparent substrate comprising at least a colored layer at a back surface of the first substrate,

said method further comprising a step of bonding an antireflection film or a polarization plate to the transparent substrate.

13. (Canceled)

14. (Original): A method according to claim 11, wherein the transparent substrate comprises a polymeric material.

15-16 (Canceled)

17. (Original) A method according to claim 11, further comprising the steps of: polishing the back surface of the substrate by a chemical mechanical polishing method.

18. (Canceled)

19. (Original): A method according to claim 12, wherein the transparent substrate comprises a polymeric material.

20. (Original) A method according to claim 12, wherein the transparent substrate comprises a polymeric material.

21-22. (Canceled)

23-45 (Withdrawn)